

WHAT IS CLAIMED IS:

1. An electronic circuit device, comprising:
internal terminals;
a board on which wirings to the internal terminals are formed;
5 an electronic component that is mounted on the board and is
connected with the internal terminals; and
an encapsulation resin with which the electronic component and the
internal terminals are encapsulated,
wherein a part of the wiring forms a ring-shaped portion, the
10 ring-shaped portion having a plurality of gaps by which the ring-shaped
portion is divided into a plurality of discontinuous ring-constituting sections,
and
wherein the plurality of ring-constituting sections are connected to
the respective internal terminals, and a coating region of the encapsulation
15 resin is surrounded with the ring-shaped portion.
2. The electronic circuit device according to claim 1, wherein the
ring-shaped portions of the wirings are formed as a multi-ring.
- 20 3. The electronic circuit device according to claim 1,
wherein the internal terminals are disposed within the ring-shaped
portion,
the wirings extend from an outside of the ring-shaped portion to the
respective internal terminals so as to be connected thereto via the
25 ring-shaped portion, and
a connecting point of the wiring extending from the internal
terminal with the ring-shaped portion and a connecting point of the wiring
extending from the outside with the ring-shaped portion are disposed at
positions different from each other.
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4. The electronic circuit device according to claim 1, wherein an
intersecting portion of the ring-shaped portion and one end of the wiring is
shaped like a letter T.
- 35 5. The electronic circuit device according to claim 2, wherein the gaps
provided in the respective wirings of the multi-ring as the ring-shaped
portion are disposed so as not to be on a same normal line with respect to

the ring-shaped portion.

6. The electronic circuit device according to claim 1, wherein the wiring is connected with a wiring on a rear face of the board via a through hole
5 formed in the board, the through hole being disposed adjacent to an outer edge of the ring-shaped portion.

7. The electronic circuit device according to claim 1, wherein the wiring is connected with a wiring on a rear face of the board via a through hole
10 formed in the board, the through hole being disposed within the ring-shaped portion.

8. The electronic circuit device according to of claim 1, wherein a part of the wiring is formed so as to divide an inner region of the ring-shaped
15 portion into a region including the internal terminals and a region not including the internal terminals.

9. The electronic circuit device according to claim 1, wherein three or more wirings are formed, and at an intersecting portion of the wirings and
20 the ring-shaped portion, two or less line segments are disposed linearly and in parallel from an outside to an inside of the ring-shaped portion.

10. The electronic circuit device according to claim 1, wherein the wiring extending on the outside of the ring-shaped portion and the ring-shaped
25 portion of the wiring intersect each other at angles of 60° or more.